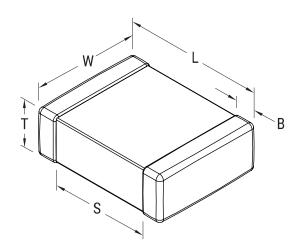


C0805J102K2RACTU

Aliases (C0805J102K2RAC7800) SMD Comm X7R FO, Ceramic, 1,000 pF, 10%, 200 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 0805, 0.6 mm



Click here for the 3D model.

General Information		
Series	SMD Comm X7R FO	
Style	SMD Chip	
Description	SMD, MLCC, Open Mode, Temperature Stable	
Features	Open Mode, Temperature Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	13 mg	
Shelf Life	78 Weeks	
MSL	1	

	Specifications	
	Capacitance	1,000 pF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	10%
	Voltage DC	200 VDC
	Dielectric Withstanding Voltage	500 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	X7R
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
	Dissipation Factor	2.5%1kHz1.0Vrms
	Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
	Insulation Resistance	100 GOhms

 Dimensions

 Chip Size
 0805

 L
 2mm +/-0.3mm

 W
 1.25mm +/-0.3mm

 T
 0.9mm +/-0.10mm

 S
 0.6mm MIN

 B
 0.5mm +/-0.25mm

Packaging Specifications Packaging

Packaging Quantity 4000	Packaging	T&R, 180mm, Plastic Tape
	Packaging Quantity	4000

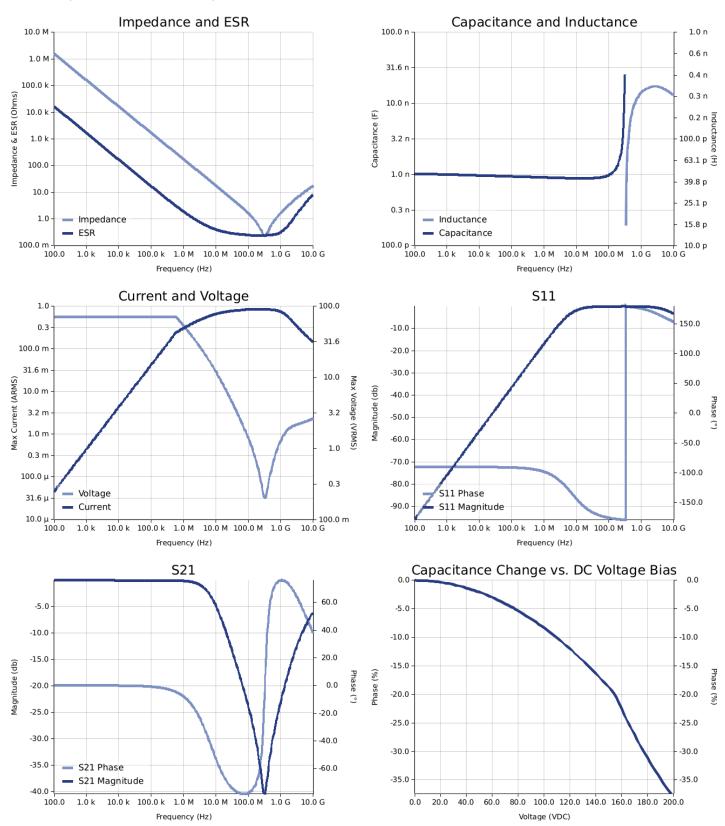
Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.



CO805J102K2RACTU Aliases (C0805J102K2RAC7800) SMD Comm X7R FO, Ceramic, 1,000 pF, 10%, 200 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 0805, 0.6 mm

Simulations

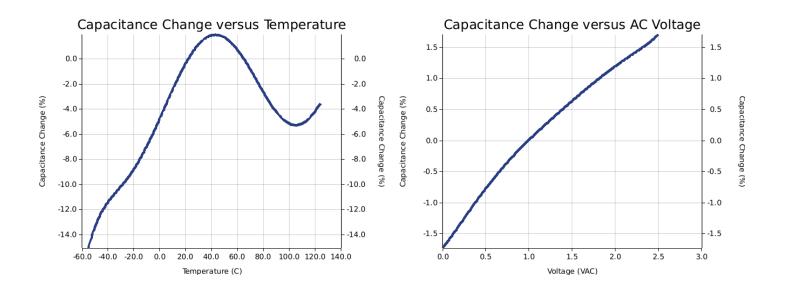
For the complete simulation environment please visit K-SIM.





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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages are not combined with voltages.
- generated at any other harmonics. Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.